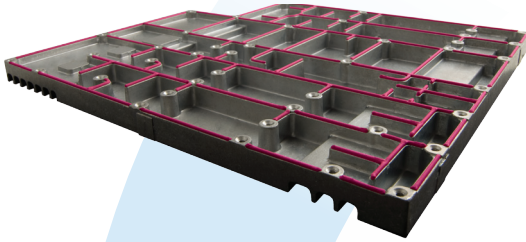


## SNC70-HXP Form-In-Place

**A rapid cure, nickel-coated graphite-filled silicone elastomer Form-In-Place gasket material.**

Laird Technologies introduces another product in the EMI Sentry family. These Form-In-Place pastes are extremely fast curing with reliable shielding effectiveness and strength

Laird Technologies' Form-In-Place is an automated system for dispensing conductive elastomer EMI shielding and grounding gaskets onto metal or plastic substrates. This product is particularly ideal for base stations, PDAs, PC cards, radios, mobile phones, as well as many other cast enclosures and packaged electronic assemblies.



\* does not represent actual color

### TYPICAL VALUES

	TEST METHOD	UNITS	SNC70-HXP
Elastomer			Silicone
Filler			Nickel/Graphite
<b>ELECTRICAL PROPERTIES</b>			
Volume Resistivity		ohm-cm	0.030
Shielding Effectiveness	MIL-DTL-83528C		
200 MHz to 10 GHz	Para. 4.5.12	dB	>90
<b>PHYSICAL PROPERTIES</b>			
Hardness	ASTM D2240	Shore A	70
Density (cured)	ASTM D792	g/cm <sup>3</sup>	2.5
Density (uncured)	LT-FIP-CLE-09	g/cm <sup>3</sup>	2.3
Compression Set	ASTM D395	%	15
Adhesion Strength (Al)	LT-FIP-CLE-03	N/cm <sup>2</sup>	>180
Compression-Deflection (a)	LT-FIP-CLE-07		
at 20% compression		lb/in	3.2
at 40% compression		lb/in	11.5
Temperature Range		°C	-50°C to 150°C
UL rating	UL-94		V0
<b>CURING REQUIREMENTS</b>			
Cure conditions		120°C minimum	
Cure Time at 125°C (b)	LT-FIP-CLE-14		1 hour

- (a) Compression-deflection bead size 0.60 mm (H) x 0.70 mm (W) rev. 07/02/09
- (b) Time to effectively cure a bead will necessarily depend on individual conditions, including but not limited to bead size, shield size and weight, oven capacity, and oven ramp-rates.

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### EMI-DS-FIP-SNC70-HXP 0113

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